IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute									ials and Mfg Information					
Supplier	Information															
Company name*				Company unique ID			Unique ID Authority					Response Date*				
onsemi												2024-04-20				
Contact Na	me	Title - Contact			I	Phone - Contact*					Email - Contact*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-E	nv-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	ctive Date		ufacturing Site	Weight*		UOI	M	Unit Type	
		NCP1083DEG POE-PD 40W DC-		DC AUX SU	ГРР	2024-04-20 BE4				75.07	mg		Each			
Manufac	turing Proccess Informa	ntion												,		
7	Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL I			ting Peak Process Body Temperature Max Time at P			Max Time at Peak	ak Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Allo			CU Alloy	oy 2			260 C 30		30	seconds 3						
Comments																
TTENTI	ON: MSL 2 Rated item require	es Dry Pack (a	fter electrical	l test)												
or more in	nformation regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not orditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty ri											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	7.34 mg		Supplier	Silicon (Si)	7440-21-3		7.34	mg
Die Attach	2.2	mg		Epoxy resin	proprietary data		0.11	mg
			Supplier	Poly(oxypropylene)diamine	9046-10-0		0.044	mg
			Supplier	Copper(II) Oxide (CuO)	1317-38-0		0.066	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.066	mg
			Supplier	Silver (Ag)	7440-22-4		1.804	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.11	mg
Lead Frame	26.7	mg	Supplier	Zinc (Zn)	7440-66-6		0.032	mg
			Supplier	Iron (Fe)	7439-89-6		0.6274	mg
			Supplier	Copper (Cu)	7440-50-8		26.0325	mg
			Supplier	Phosphorus (P)	7723-14-0		0.008	mg
Mold Compound-Black	37.18	mg		Epoxy resin	proprietary data		2.7885	mg
			Supplier	Phenolic Resin	Proprietary Data		0.9295	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.7885	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1859	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		30.4876	mg
Plating	1.1	mg	Supplier	Tin (Sn)	7440-31-5		1.1	mg
Wire Bond - Au	0.55	mg	Supplier	Gold (Au)	7440-57-5		0.55	mg